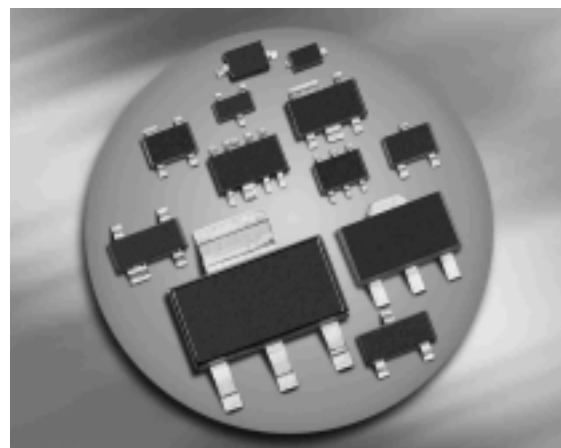


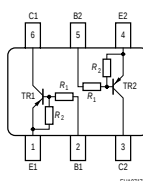
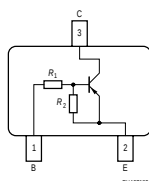
PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ($R_1 = 10\text{ k}\Omega$, $R_2 = 47\text{ k}\Omega$)
- BCR185S / U: Two internally isolated transistors with good matching in one multichip package
- BCR185S / U: For orientation in reel see package information below



BCR185/F/L3 BCR185T/W

BCR185S/U



Type	Marking	Pin Configuration						Package
BCR185	WNs	1=B	2=E	3=C	-	-	-	SOT23
BCR185F	WNs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR185L3	WN	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR185S	WNs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR185T	WN	1=B	2=E	3=C	-	-	-	SC75
BCR185U	WNs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74
BCR185W	WNs	1=B	2=E	3=C	-	-	-	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	6	
Collector current	I_C	100	mA
Total power dissipation- BCR185 $T_S \leq 102^\circ\text{C}$ BCR185F, $T_S \leq 128^\circ\text{C}$ BCR185L3, $T_S \leq 135^\circ\text{C}$ BCR185S, $T_S \leq 115^\circ\text{C}$ BCR185T, $T_S \leq 109^\circ\text{C}$ BCR185U, $T_S \leq 118^\circ\text{C}$ BCR185W, $T_S \leq 124^\circ\text{C}$	P_{tot}	200 250 250 250 250 250 250	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BCR185		≤ 240	
BCR185F		≤ 90	
BCR185L3		≤ 60	
BCR185S		≤ 140	
BCR185T		≤ 165	
BCR185U		≤ 133	
BCR185W		≤ 105	

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

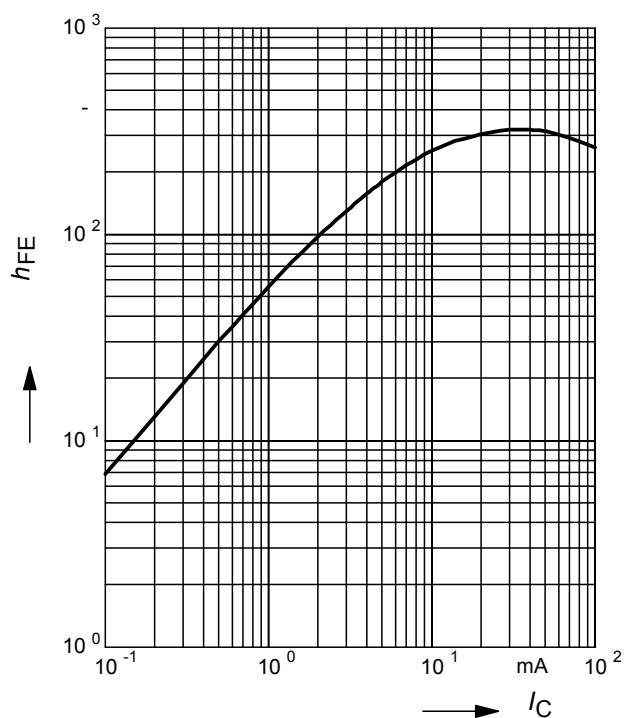
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100\ \mu\text{A}$, $I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10\ \mu\text{A}$, $I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{\text{CB}} = 40\ \text{V}$, $I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{\text{EB}} = 6\ \text{V}$, $I_C = 0$	I_{EBO}	-	-	167	μA
DC current gain ¹⁾ $I_C = 5\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$	h_{FE}	70	-	-	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10\ \text{mA}$, $I_B = 0.5\ \text{mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100\ \mu\text{A}$, $V_{\text{CE}} = 5\ \text{V}$	$V_{\text{i(off)}}$	0.5	-	1	
Input on voltage $I_C = 2\ \text{mA}$, $V_{\text{CE}} = 0.3\ \text{V}$	$V_{\text{i(on)}}$	0.5	-	1.4	
Input resistor	R_1	7	10	13	k Ω
Resistor ratio	R_1/R_2	0.19	0.21	0.24	-
AC Characteristics					
Transition frequency $I_C = 10\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$, $f = 100\ \text{MHz}$	f_{T}	-	200	-	MHz
Collector-base capacitance $V_{\text{CB}} = 10\ \text{V}$, $f = 1\ \text{MHz}$	C_{cb}	-	3	-	pF

¹⁾Pulse test: $t < 300\ \mu\text{s}$; $D < 2\%$

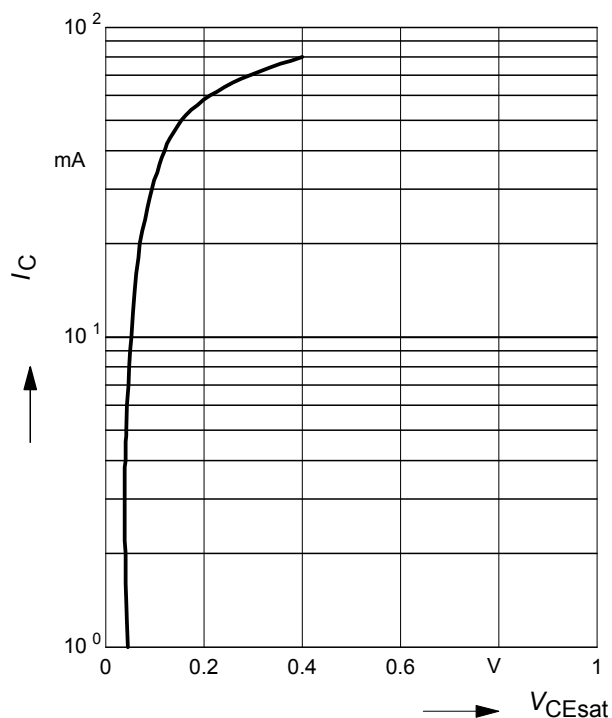
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)



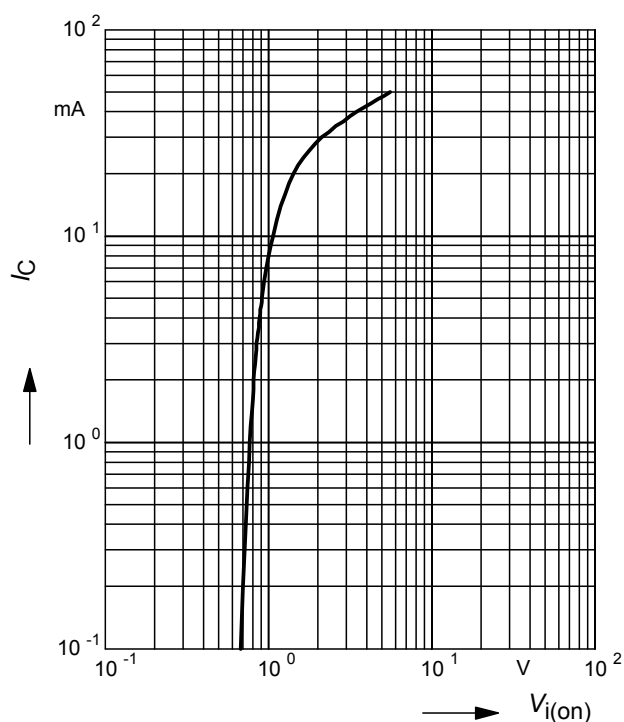
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, $h_{FE} = 20$



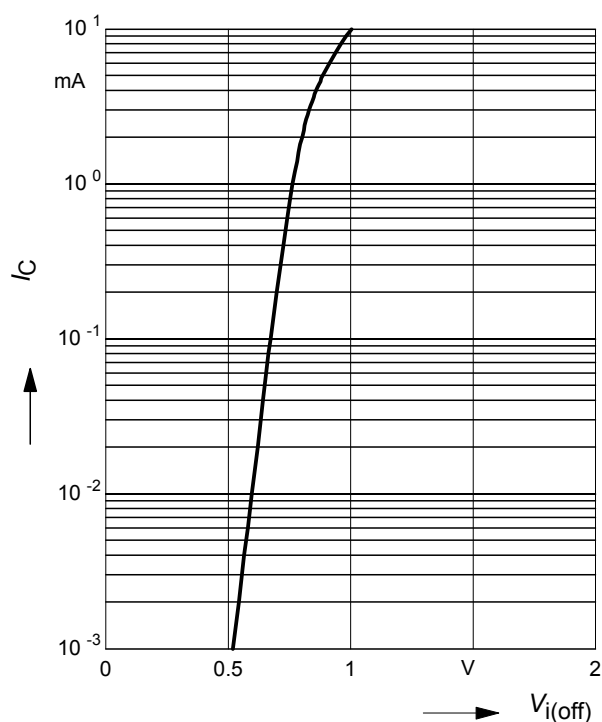
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3\text{ V}$ (common emitter configuration)



Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)



Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185



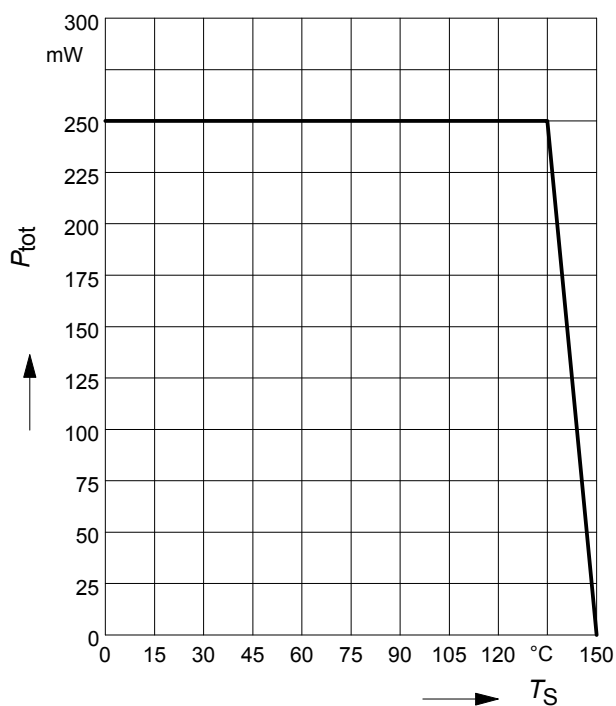
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185F



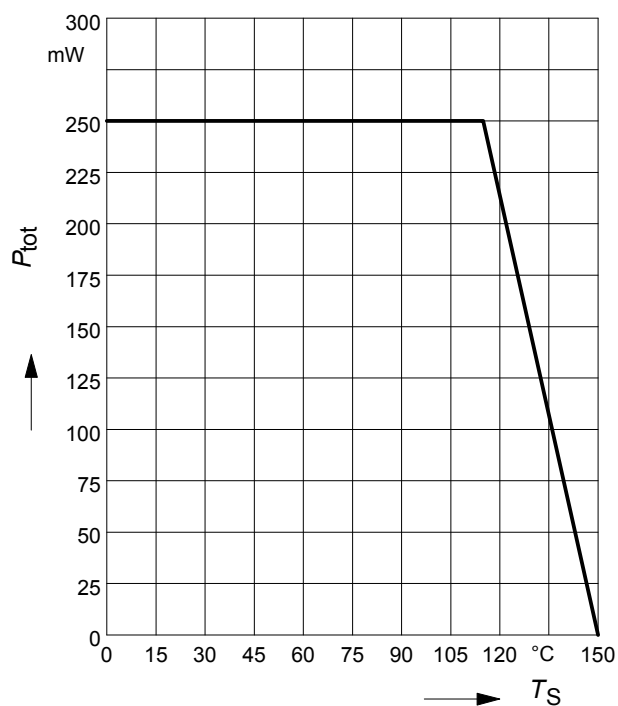
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185L3



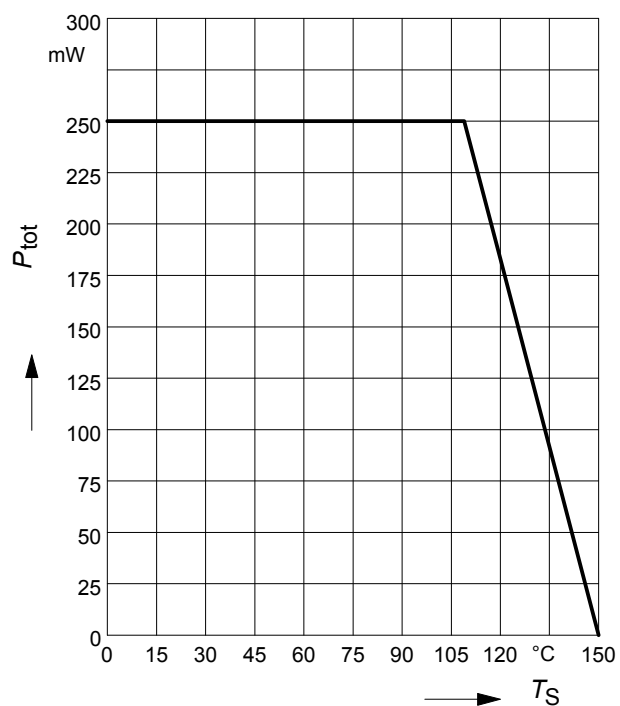
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185S



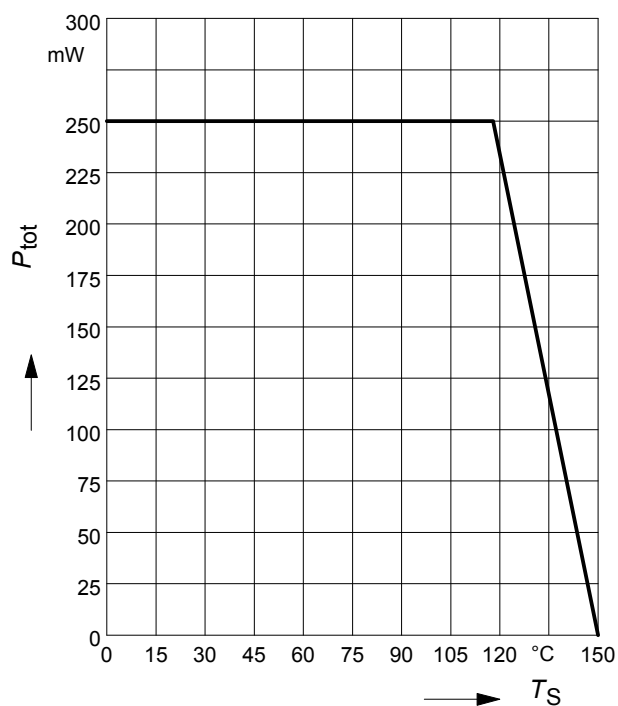
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185T



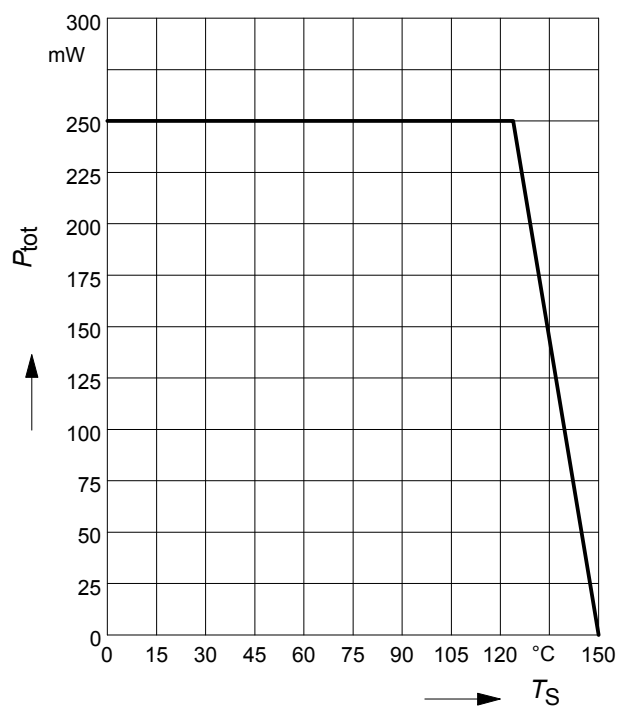
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185U



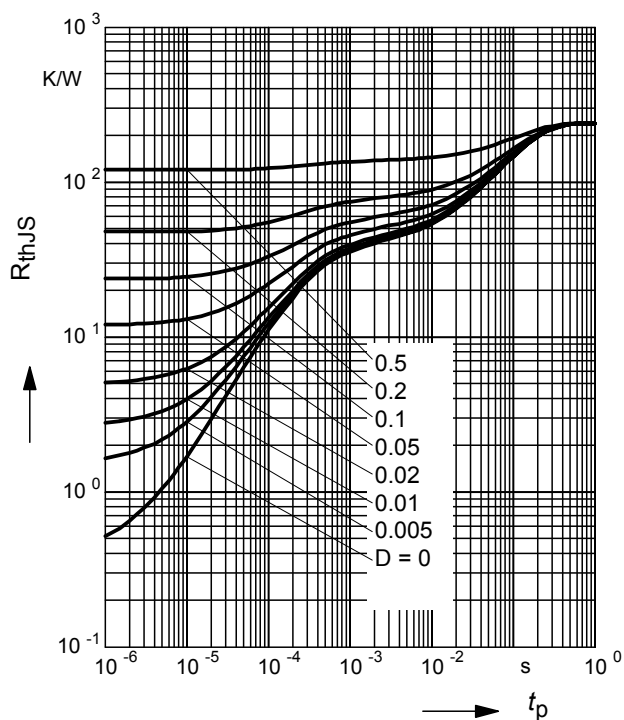
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR185W



Permissible Pulse Load $R_{thJS} = f(t_p)$

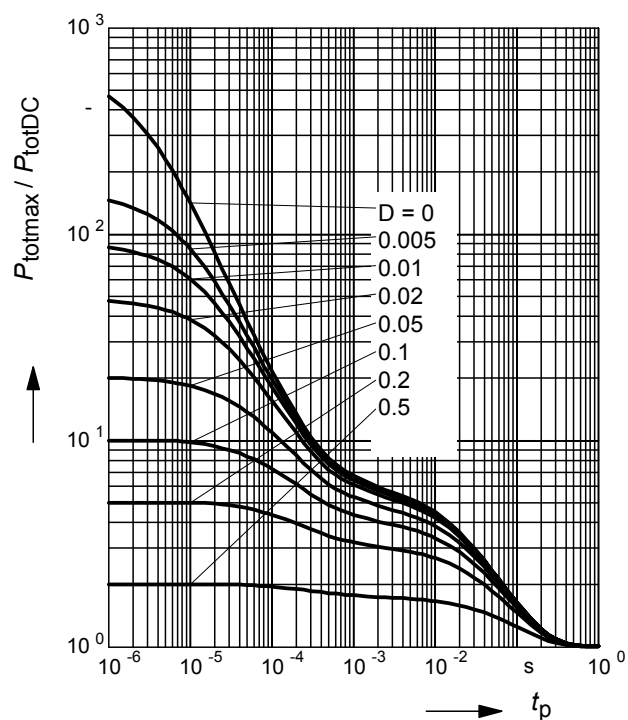
BCR185



Permissible Pulse Load

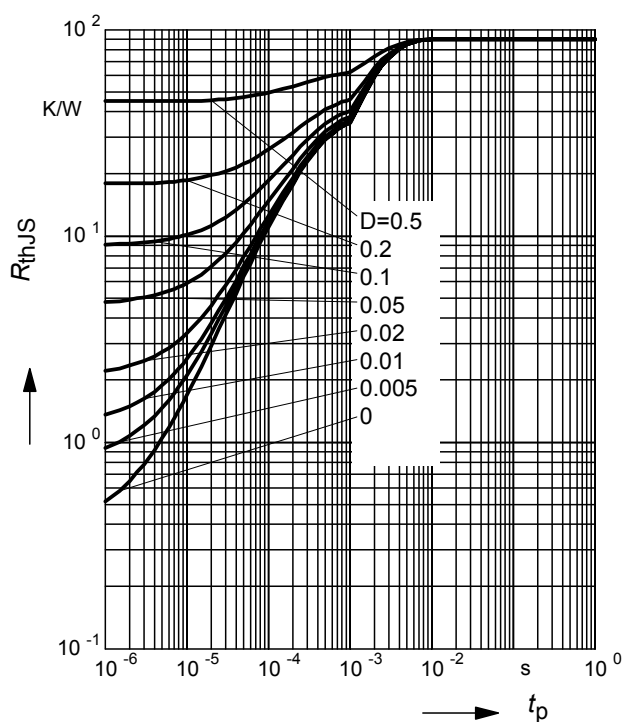
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185



Permissible Puls Load $R_{thJS} = f(t_p)$

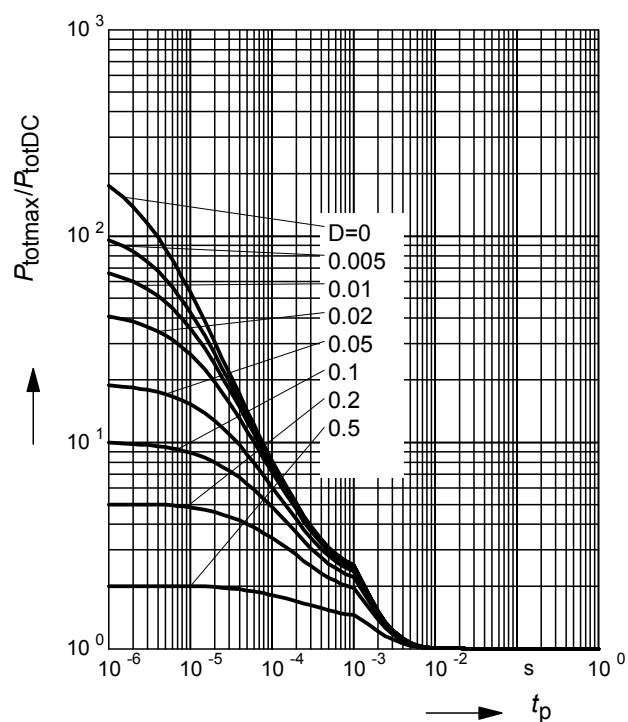
BCR185F



Permissible Pulse Load

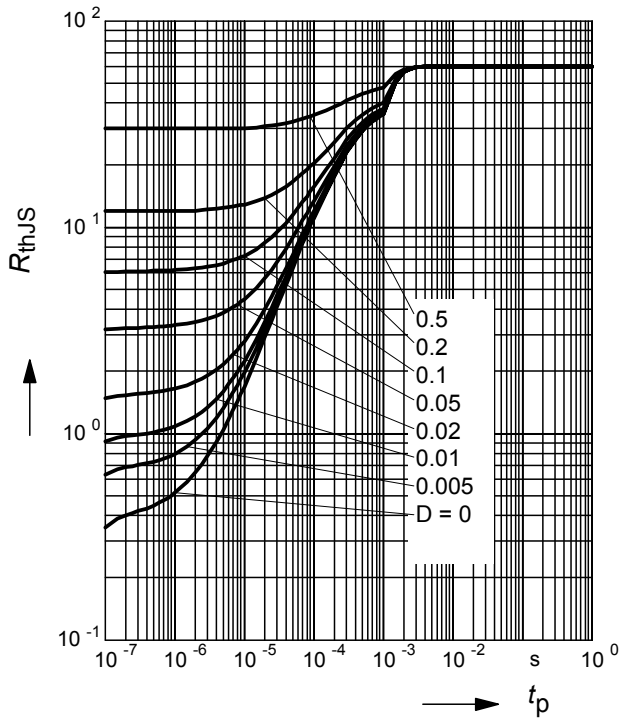
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185F



Permissible Puls Load $R_{thJS} = f(t_p)$

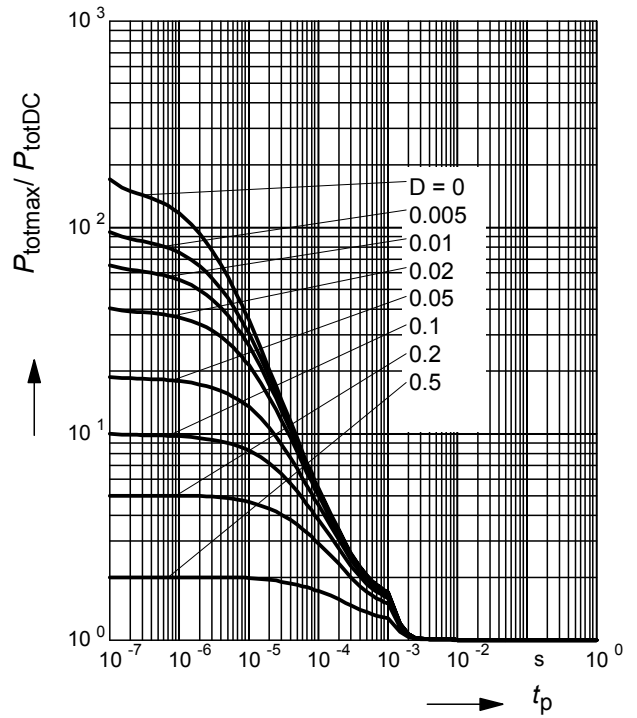
BCR185L3



Permissible Pulse Load

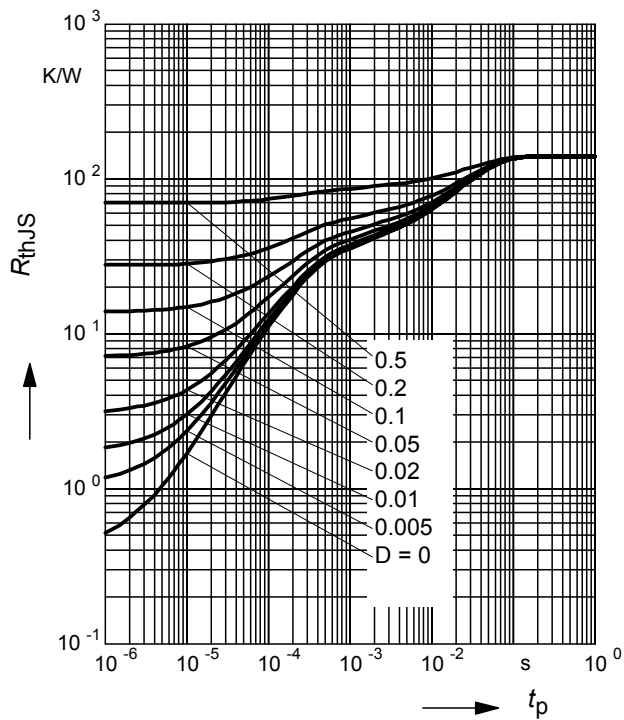
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185L3



Permissible Puls Load $R_{thJS} = f(t_p)$

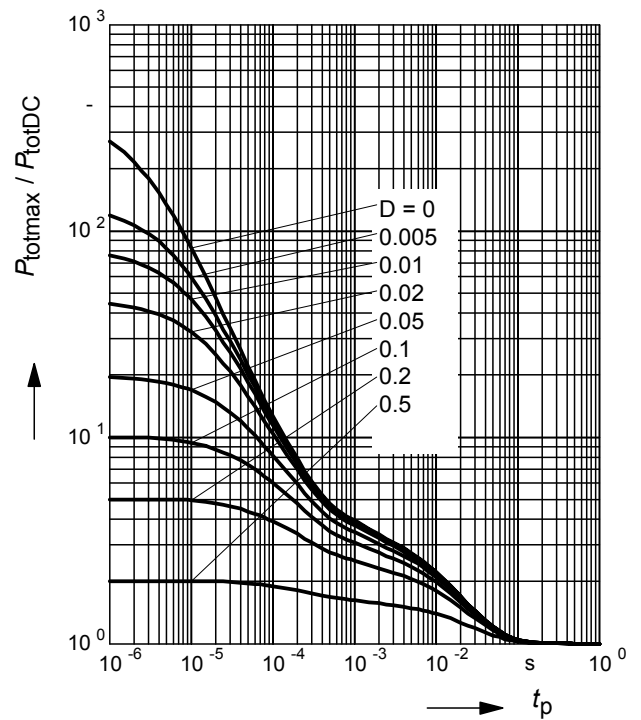
BCR185S



Permissible Pulse Load

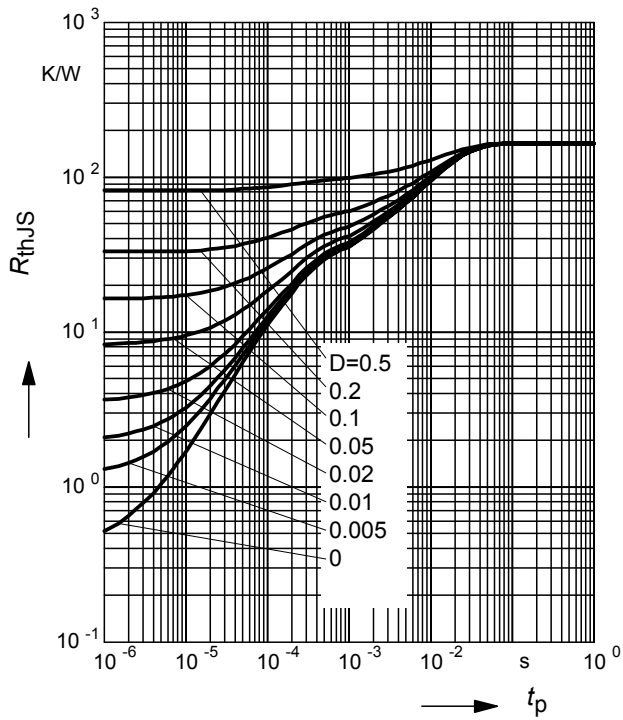
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185S



Permissible Puls Load $R_{thJS} = f(t_p)$

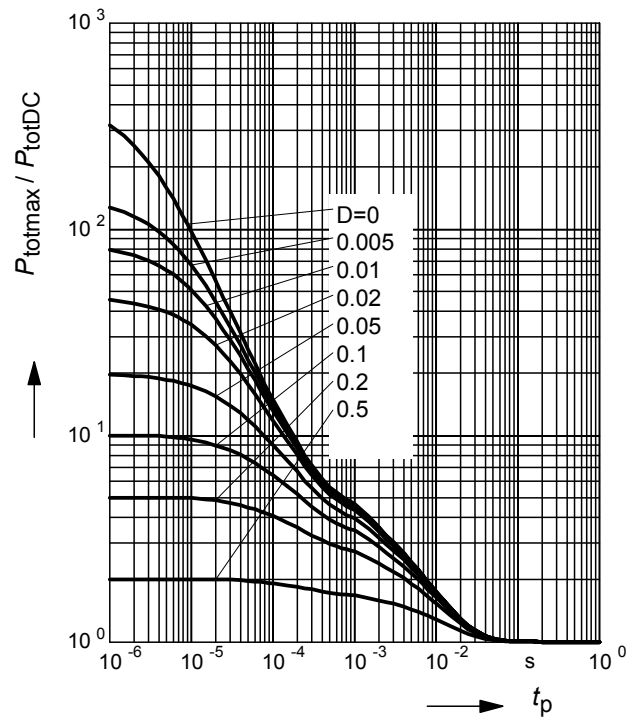
BCR185T



Permissible Pulse Load

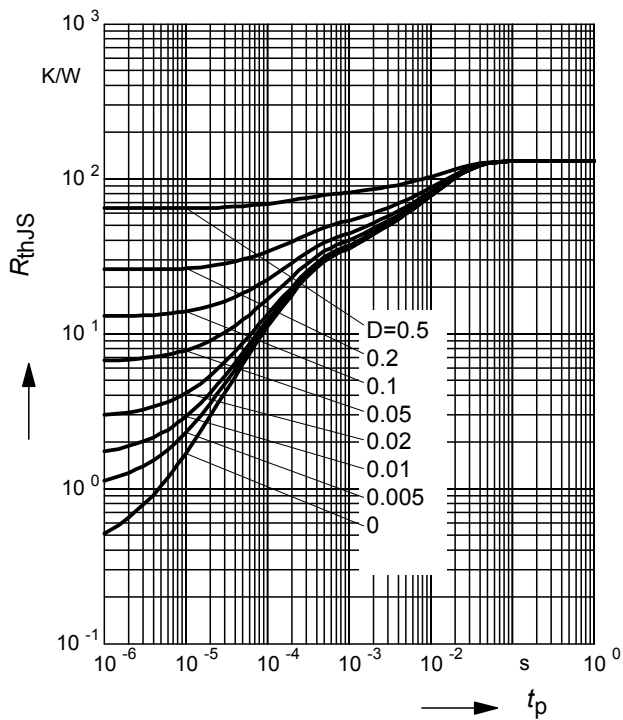
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185T



Permissible Puls Load $R_{thJS} = f(t_p)$

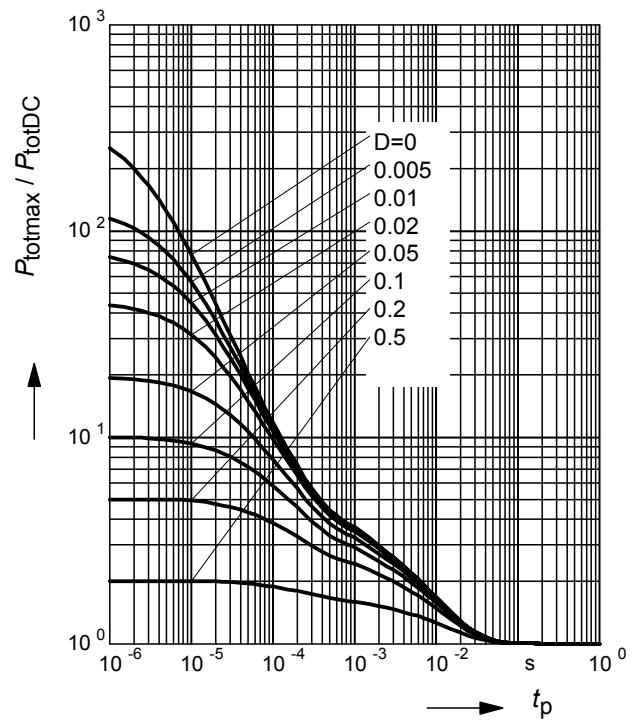
BCR185U



Permissible Pulse Load

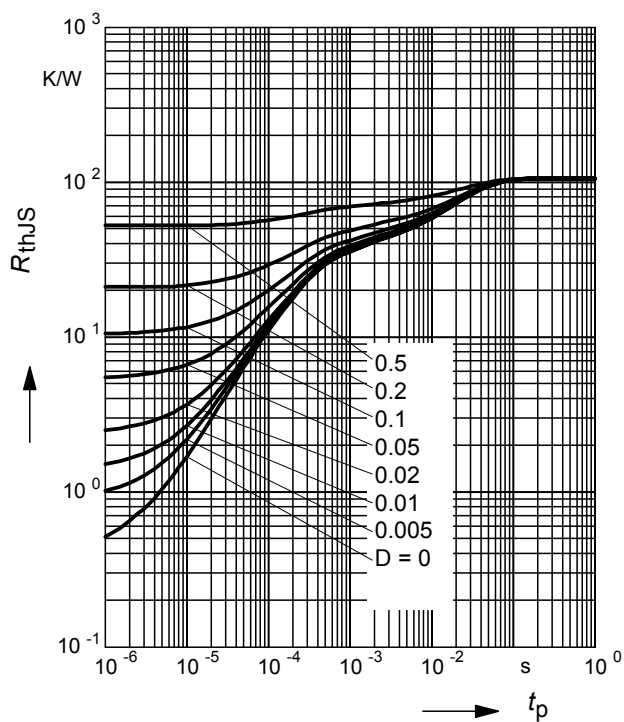
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR185U



Permissible Puls Load $R_{thJS} = f(t_p)$

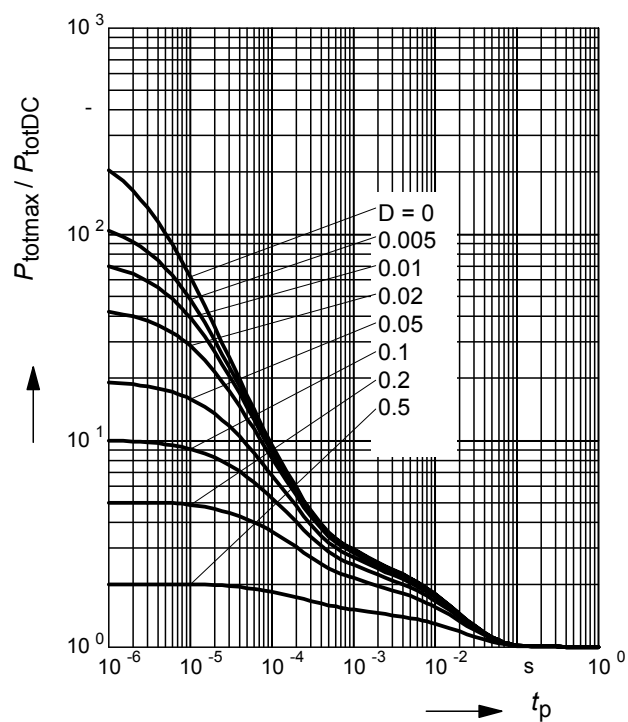
BCR185W



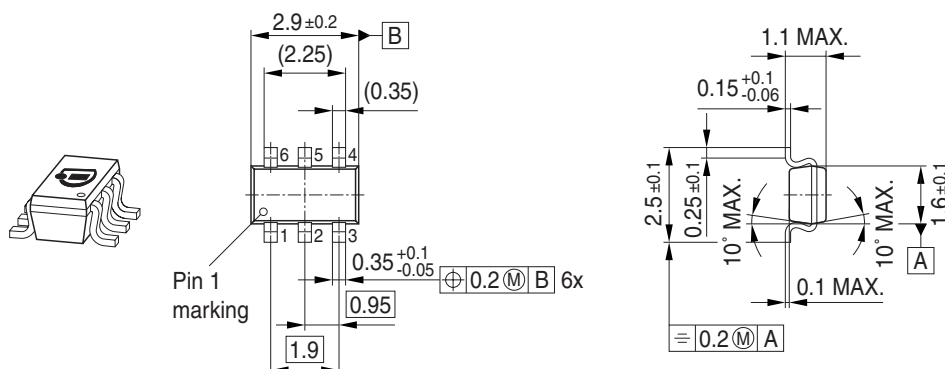
Permissible Pulse Load

$$P_{totmax}/P_{totDC} = f(t_p)$$

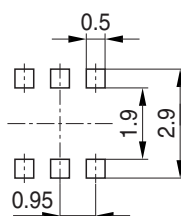
BCR185W



Package Outline

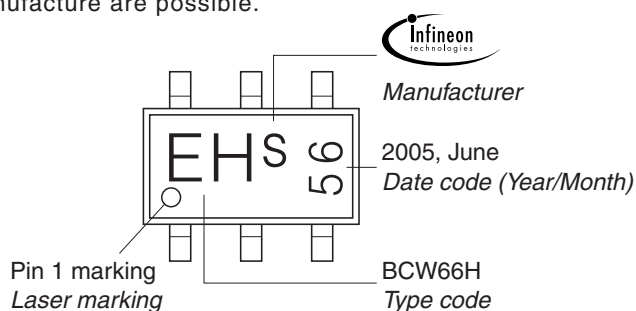


Foot Print



Marking Layout (Example)

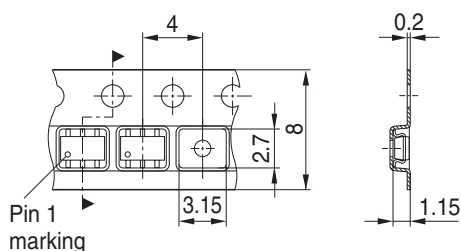
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

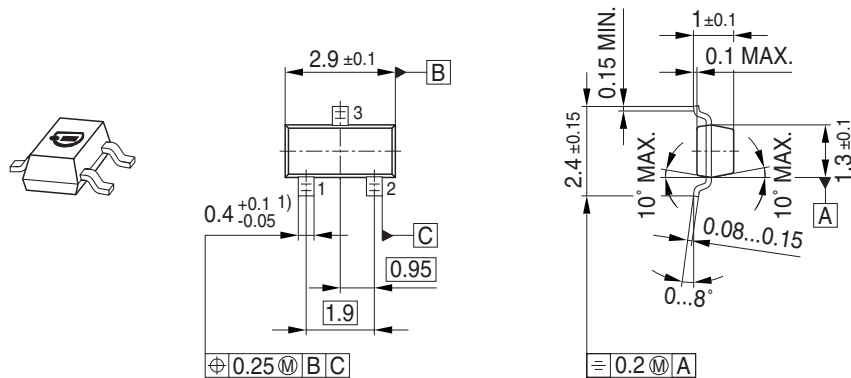


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

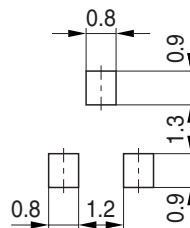
1) New Marking Layout for SC75, implemented at October 2005.

Package Outline

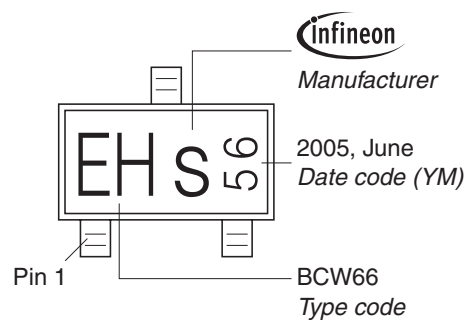


1) Lead width can be 0.6 max. in dambar area

Foot Print

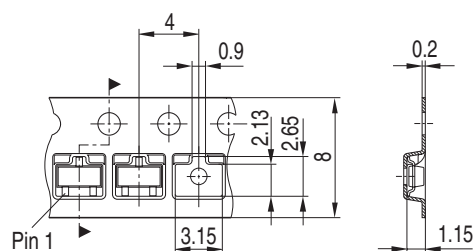


Marking Layout (Example)

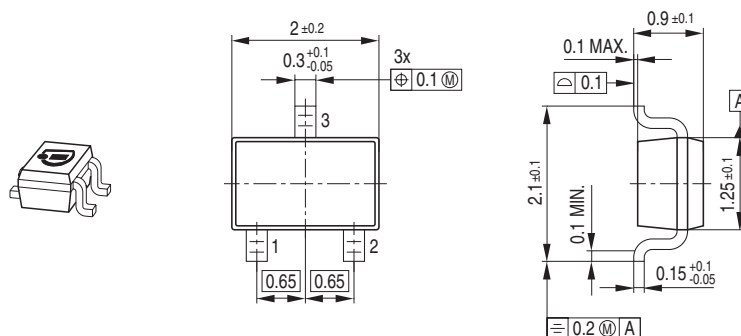


Standard Packing

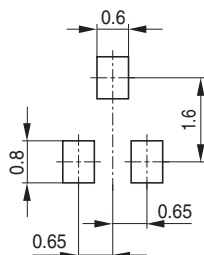
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



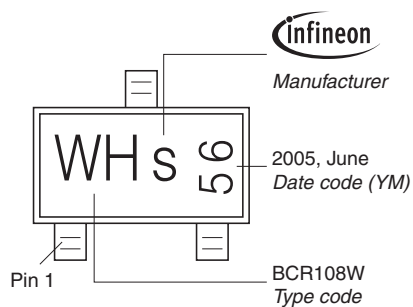
Package Outline



Foot Print

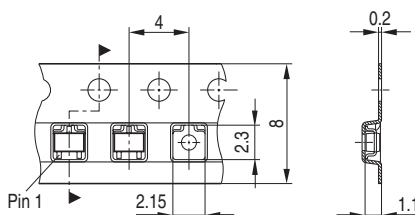


Marking Layout (Example)

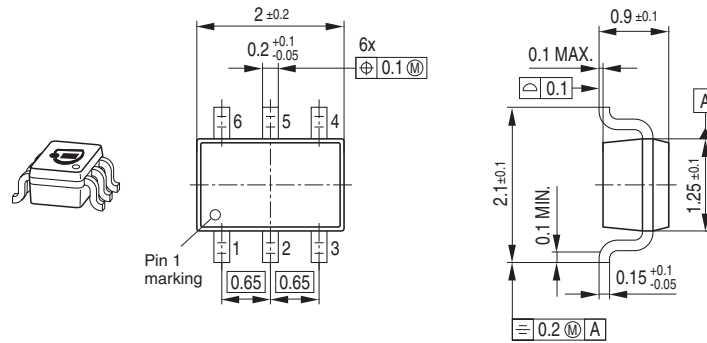


Standard Packing

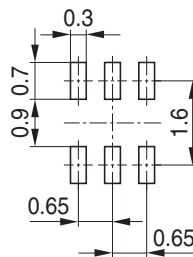
Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



Package Outline

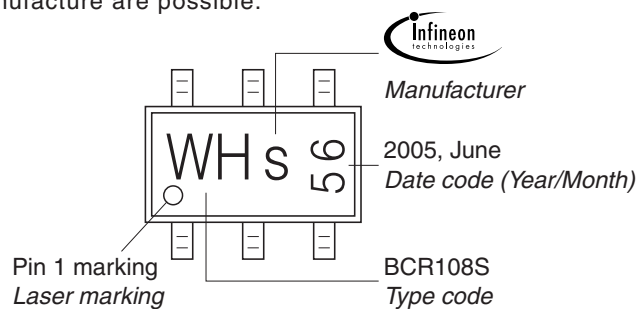


Foot Print



Marking Layout (Example)

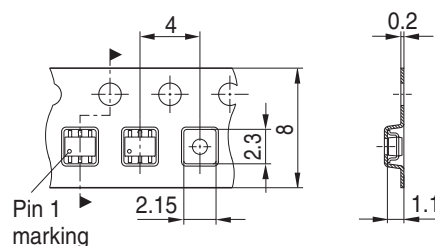
Small variations in positioning of Date code, Type code and Manufacture are possible.



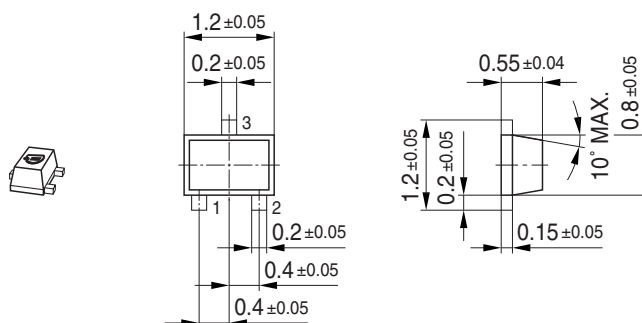
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

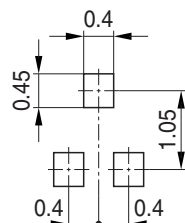
For symmetric types no defined Pin 1 orientation in reel.



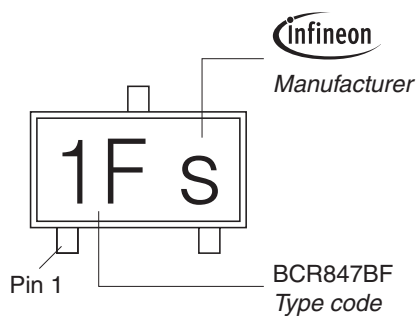
Package Outline



Foot Print

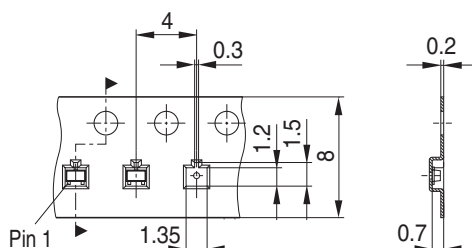


Marking Layout (Example)

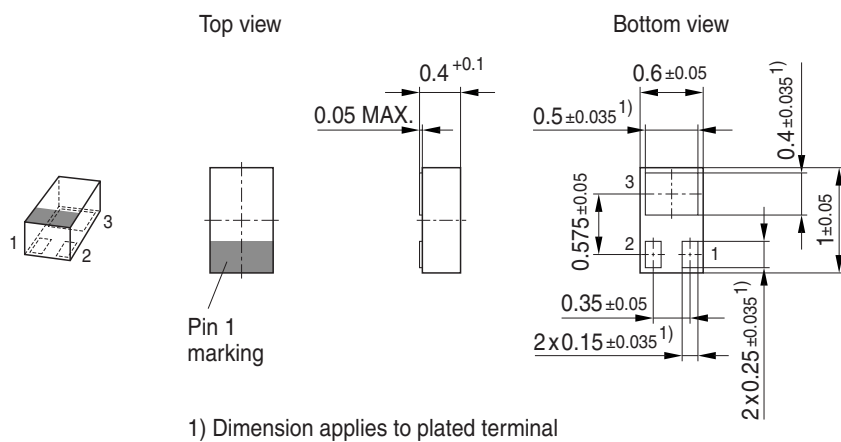


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel

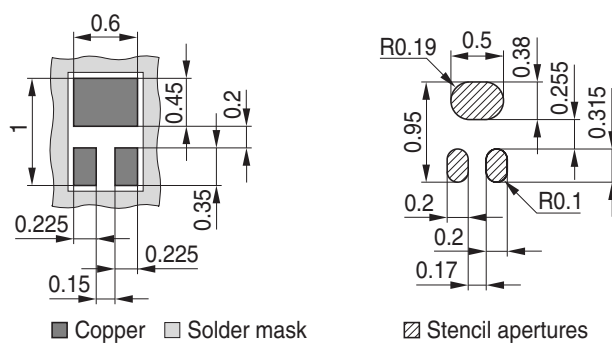


Package Outline

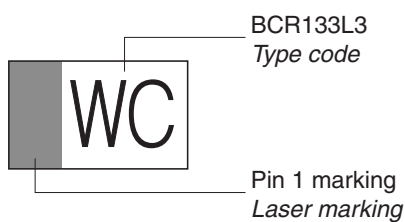


Foot Print

For board assembly information please refer to Infineon website "Packages"

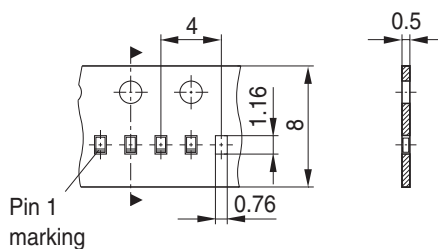


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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